



Silicon Crystal & Compound Semiconductor

➤ Gallium Nitride (GaN) Substrate

Gallium Nitride substrate as a cutting-edge new generation direct bandgap compound semiconductor material, adopted HVPE and MOCVD growing methods normally on Al₂O₃ (Sapphire) substrate, with significant higher thermal conductivity and radiation resistance, more stable chemical characteristics advantages, which can be widely used for the new type high speed and capacity LED components, power devices and RF devices. Standard 2" & 4" free-standing substrates, 2", 4" & 6" compound wafer are available.



No.	Items of Free-standing Substrate	Standard Specifications		
1	Shape	Circular	Circular	Square
2	Size mm	(2") 50.8+/-0.5	(4") 100+/-0.5	10x10 or 10x5
3	Orientation	C-plane (0001)	C-plane (0001)	C-plane (0001)
4	Conductivity Type	N	N	N or Semi-insulating
5	Dopant	Un-doped or Si	Un-doped or Si	Un-doped or Si or Fe
6	Resistivity (at 300K) Ω·cm	<0.1, <0.05	<0.1, <0.05	<0.1, <0.05, >1E6
7	Thickness μm	350+/-25	350+/-25	350+/-25
8	TTV μm max	15	15	15
9	Bow μm max	20	20	20
10	EPD cm ⁻²	<5E8	<5E8	<5E8
11	Surface Finish	P/E or P/P	P/E or P/P	P/E or P/P
12	Packing	Single wafer container inside, carton box outside.		

No.	Items of Compound Wafer	Standard Specifications		
1	Shape	Circular	Circular	Circular
2	Size mm	(2") 50.8+/-0.5	(4") 100+/-0.5	(6") 150+/-0.5
3	Orientation	C-plane (0001)	C-plane (0001)	C-plane (0001)
4	Substrate Structure	Sapphire	Sapphire	Sapphire
5	Conductivity Type	N	N	N
6	Dopant	Un-doped or Si	Un-doped or Si	Un-doped or Si
7	Resistivity (at 300K) Ω·cm	<0.5, <0.1, <0.05	<0.5, <0.1, <0.05	<0.5, <0.1, <0.05
8	Thickness μm	4.5+/-0.5, 20+/-2	4.5+/-0.5, 20+/-2	4.5+/-0.5, 20+/-2
9	TTV μm max	15	15	15
10	Bow μm max	20	20	20
11	Carrier Concentration cm ⁻³	<5E17	<5E17	<5E17
12	Hall Mobility cm ² /V.s	300	300	300
13	EPD cm ⁻²	<5E8	<5E8	<5E8
14	Effective Area	>90%	>90%	>90%
15	Surface Finish	P/E or P/P	P/E or P/P	P/E or P/P
16	Packing	Single wafer container inside, carton box outside.		